

RELIABILITY REPORT
FOR
MAX292EWE+
PLASTIC ENCAPSULATED DEVICES

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MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

Approved by
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Conclusion

The MAX292EWE+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX291/MAX292/MAX295/MAX296 are easy-to-use, 8th-order, lowpass, switched-capacitor filters that can be set up with corner frequencies from 0.1Hz to 25kHz (MAX291/MAX292) or 0.1Hz to 50kHz (MAX295/MAX296). The MAX291/MAX295 Butterworth filters provide maximally flat passband response, and the MAX292/MAX296 Bessel filters provide low overshoot and fast settling. All four filters have fixed responses, so the design task is limited to selecting the clock frequency that controls the filter's corner frequency. An external capacitor is used to generate a clock using the internal oscillator, or an external clock signal can be used. An uncommitted operational amplifier (noninverting input grounded) is provided for building a continuous time lowpass filter for post-filtering or anti-aliasing. Produced in an 8-pin DIP/SO and a 16-pin wide SO package, and requiring a minimum of external components, the MAX291 series delivers very aggressive performance from a tiny area.

II. Manufacturing Information

A. Description/Function:	8th-Order, Lowpass, Switched-Capacitor Filters
B. Process:	S3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia or Philippines
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	16-pin SOIC (W)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0201-0113
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	105 °C/W
K. Single Layer Theta Jc:	22 °C/W
L. Multi Layer Theta Ja:	71 °C/W
M. Multi Layer Theta Jc:	23 °C/W

IV. Die Information

A. Dimensions:	89X95 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 13.7 \times 10^{-9}$$

$$\lambda = 13.7 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.03 @ 25C and 0.5 @ 55C (0.8 eV, 60% UCL).

B. E.S.D. and Latch-Up Testing (lot NGKAKA179A, D/C 0232)

The AF11 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-150mA.

Table 1
Reliability Evaluation Test Results

MAX292EWE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	NGKK4175AQ, D/C 0206

Note 1: Life Test Data may represent plastic DIP qualification lots.